



# N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
30	0.0195 at V <sub>GS</sub> = 10 V	8	9.2 nC			
30	0.023 at V <sub>GS</sub> = 4.5 V	8	9.2110			

#### **FEATURES**

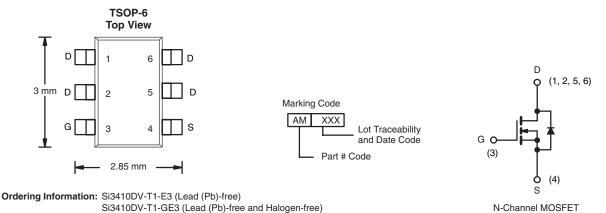
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Compliant to RoHS Directive 2002/95/EC

# RoHS COMPLIANT HALOGEN

FREE

#### **APPLICATIONS**

- · Notebook Load Switch
- Low Current dc-to-dc



<b>ABSOLUTE MAXIMUM RATINGS</b> T	$_{A}$ = 25 $^{\circ}$ C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		8 <sup>a</sup>	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C		8 <sup>a</sup>	
Continuous Diam Current (1) = 150 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	7.5 <sup>b,c</sup>	
	T <sub>A</sub> = 70 °C		5.9 <sup>b,c</sup>	Α
Pulsed Drain Current	I <sub>DM</sub>	30		
Ocaliano Come Paris Diede Ocale	T <sub>C</sub> = 25 °C	1	2.7	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	l <sub>s</sub>	1.7 <sup>b,c</sup>	
	T <sub>C</sub> = 25 °C		4.1	
Maximum Dawar Dissination	T <sub>C</sub> = 70 °C	ь —	2.6	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2 <sup>b,c</sup>	VV
	T <sub>A</sub> = 70 °C		1.25 <sup>b,c</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	$R_{thJA}$	45	62.5	°C/W		
Maximum Junction-to-Foot	Steady State	$R_{thJF}$	25	30	C/VV		

#### Notes

- a. Package Limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under Steady State conditions is 110  $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	e/Tı		33		m\//°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 6.2		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		3	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Cata Valtana Busin Comment	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	, , , ^
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α
Davis Course Or Otala Basislana 3	D	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.016	0.0195	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.019	0.023	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		24		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1295		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		170		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			72		
Total Cata Chausa	Q <sub>g</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		21.8	33	
Total Gate Charge				9.2	14	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		3.8		nC
Gate-Drain Charge	$Q_{gd}$			2.5		
Gate Resistance	$R_{g}$	f = 1 MHz		2.4		Ω
Turn-On Delay Time	t <sub>d(on)</sub>			21	40	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$		14	25	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D\cong 5$ A, $V_{GEN}=4.5$ V, $R_g=1$ $\Omega$		20	40	
Fall Time	t <sub>f</sub>			9	18	1
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	ns
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 3 $\Omega$		8	16	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		21	35	
Fall Time	t <sub>f</sub>	-		8	16	1
<b>Drain-Source Body Diode Characterist</b>	ics					
Continous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.7	^
Pulse Diode Forward Current	I <sub>SM</sub>				30	Α
Body Diode Voltage	$V_{SD}$	$I_S = 1.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.77	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			21	40	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 3 A, dl/dt = 100 A/μs, T <sub>.I</sub> = 25 °C		15	30	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 3 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, I_J = 25 \text{ C}$		13		ns
Reverse Recovery Rise Time	t <sub>b</sub>			8		

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

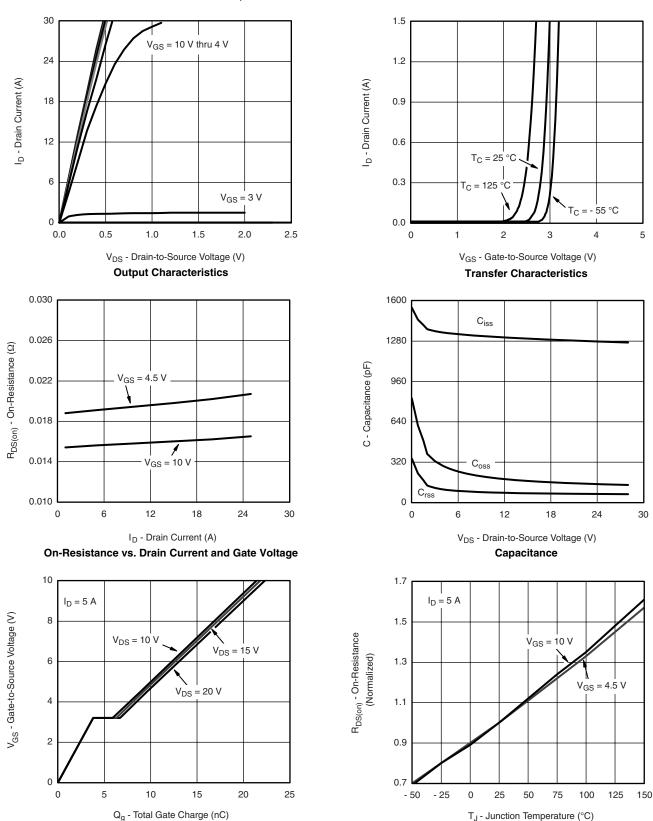
a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.





#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



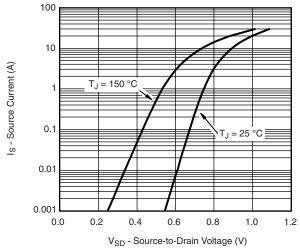
**Gate Charge** 

On-Resistance vs. Junction Temperature

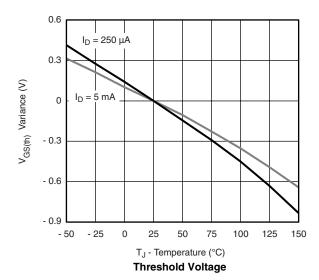
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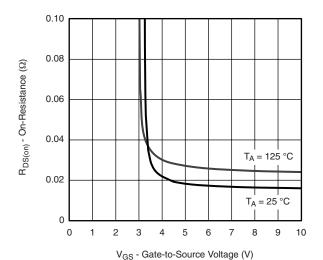
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

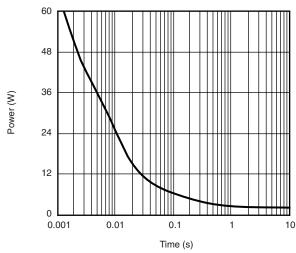


#### Source-Drain Diode Forward Voltage

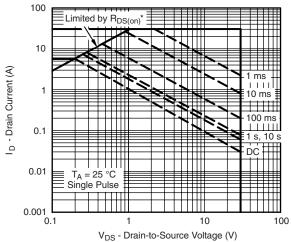




On-Resistance vs. Gate-to-Source Temperature



Single Pulse Power, Junction-to-Ambient



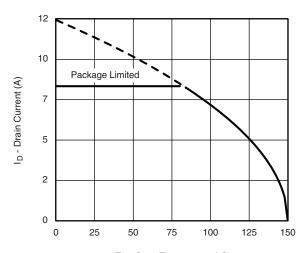
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient



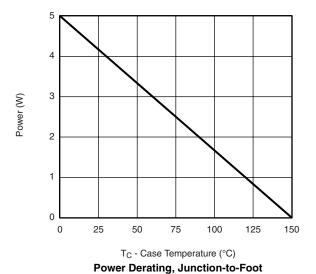


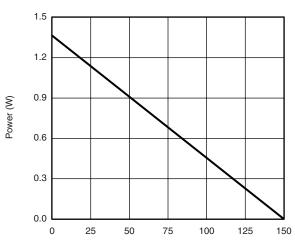
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$  - Case Temperature (°C)

#### **Current Derating\***





 $T_A$  - Ambient Temperature (°C)  $\label{eq:TA} \mbox{Power Derating, Junction-to-Ambient}$ 

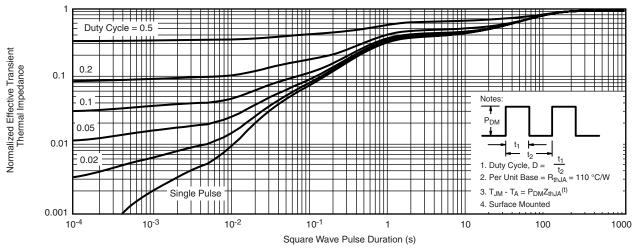
Document Number: 69254 S09-2110-Rev. B, 12-Oct-09

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

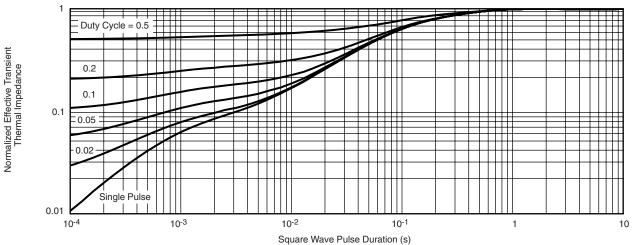
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

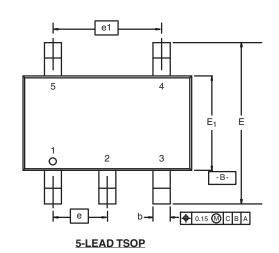
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?69254">www.vishay.com/ppg?69254</a>.

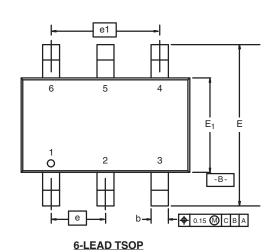


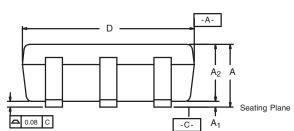


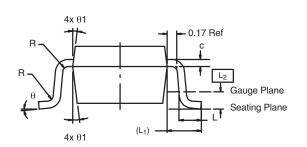
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 









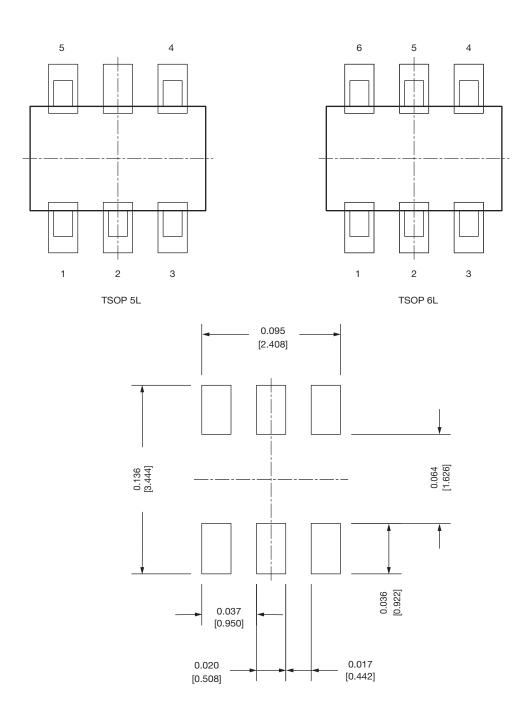
	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004	
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
E	2.70	2.85	2.98	0.106	0.112	0.117	
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e <sub>1</sub>	1.80	1.90	2.00	0.071 0.075 0.0			
L	0.32	-	0.50	0.012	-	0.020	
L <sub>1</sub>	0.60 Ref			0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
$\theta_1$	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

Document Number: 71200

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## Recommended Land Pattern For TSOP-5L / TSOP-6L



#### Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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